

Application No. 09/921,358

Reply to Office Action

*AMENDMENTS TO THE CLAIMS*

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Previously Presented) A flexible metal-clad laminate comprising a metal foil and a heat-resistant resin film layer formed on one side of the metal foil, produced by applying a solution containing an organic solvent and a condensation polymer to the metal foil and drying the laminate, the heat-resistant resin film layer comprising a crosslinked condensation polymer and having an N-methyl-2-pyrrolidone-insoluble content of at least 1%, wherein

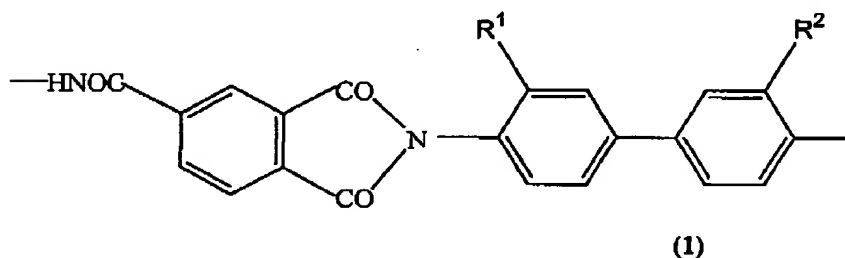
the flexible metal-clad laminate has a radius of curvature of at least 15 cm,

the heat-resistant resin film layer has a thermal gradient dimensional change of not more than 0.1% when heated at 200 °C for 30 minutes,

the average surface roughness Ra of the surface of the heat-resistant resin film layer which is in contact with the metal foil is not more than 0.4 µm,

the thickness of the metal foil is from 3 to 50 µm, and

the condensation polymer comprises the unit represented by formula (1)



wherein R<sup>1</sup> and R<sup>2</sup> are the same and each represents a methyl group.

2. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat resistant resin film layer is formed by converting an organic solvent-soluble condensation polymer by crosslinking into an organic solvent-insoluble form.

3. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat-resistant resin film layer is formed by applying to the metal foil a solution prepared by dissolving an organic solvent-soluble condensation polymer in the organic solvent and

Application No. 09/921,358

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subjecting the coated metal foil to a predrying step, and a heat-treatment and solvent removal step.

4. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat-resistant resin film layer has an initiation tear strength (film thickness: 20  $\mu\text{m}$ ) of at least 15 kg and has a thermal gradient dimensional change of not more than 0.1% when heated at 200°C for 30 minutes.

5. (Original) The flexible metal-clad laminate according to claim 1, which has a solder heat resistance of at least 350°C, an adhesion between the metal foil and the heat-resistant resin film of at least 80 g/mm and a radius of curvature of at least 15 cm.

6. (Cancelled)

7. (Original) The flexible metal-clad laminate according to claim 1, wherein the elastic modulus retentivity of the heat-resistant resin film after being immersed in an aqueous solution of sodium hydroxide (40% by weight) at 25°C for 100 hours is at least 40%.

8.-17. (Cancelled)

18. (Previously Presented) A flexible printed wiring board comprising the flexible metal-clad laminate according to claim 1.

19.-26. (Cancelled)